CD54/74HC123, CD54/74HCT123, CD74HC423, CD74HCT423

Data sheet acquired from Harris Semiconductor
SCHS142F

September 1997 - Revised October 2003

High-Speed CMOS Logic Dual Retriggerable Monostable Multivibrators with Resets

Features

- **Overriding Reset Terminates Output Pulse**
- **Triggering From the Leading or Trailing Edge**
- **Q and $\overline{Q}$ Buffered Outputs**
- **Separate Resets**
- **Wide Range of Output-Pulse Widths**
- **Schmitt Trigger on Both $\overline{A}$ and B Inputs**
- **Fanout (Over Temperature Range)**
  - **Standard Outputs . . . . . 10 LSTTL Loads**
  - **Bus Driver Outputs . . . . . 15 LSTTL Loads**
- **Wide Operating Temperature Range . . . -55^{o}C to 125^{o}C**
- **Balanced Propagation Delay and Transition Times**
- **Significant Power Reduction Compared to LSTTL Logic ICs**
- **HC Types**
  - **2V to 6V Operation**
  - **High Noise Immunity: N_{IL} = 30%, N_{IH} = 30%of V_{CC} at V_{CC} = 5V**
- **HCT Types**
  - **4.5V to 5.5V Operation**
  - **Direct LSTTL Input Logic Compatibility, V_{IL}= 0.8V (Max), V_{IH} = 2V (Min)**
  - **CMOS Input Compatibility, $I_I \leq 1\mu A$ at V_{OL}, V_{OH}**

Description

The 'HC123, 'HCT123, CD74HC423 and CD74HCT423 are dual monostable multivibrators with resets. They are all retriggerable and differ only in that the 123 types can be triggered by a negative to positive reset pulse; whereas the 423 types do not have this feature. An external resistor (R_X) and an external capacitor (C_X) control the timing and the accuracy for the circuit. Adjustment of Rx and C_X provides a wide range of output pulse widths from the Q and $\overline{Q}$ terminals. Pulse triggering on the $\overline{A}$ and B inputs occur at a particular voltage level and is not related to the rise and fall times of the trigger pulses.

Once triggered, the output pulse width may be extended by retriggering inputs $\overline{A}$ and B. The output pulse can be terminated by a LOW level on the Reset (R) pin. Trailing edge triggering ($\overline{A}$) and leading edge triggering (B) inputs are provided for triggering from either edge of the input pulse. If either Mono is not used each input on the unused device ($\overline{A}$, B, and $\overline{R}$) must be terminated high or low.

The minimum value of external resistance, Rx is typically 5kΩ. The minimum value external capacitance, CX, is 0pF. The calculation for the pulse width is $t_W = 0.45\ R_X C_X$ at V_{CC} = 5V.

Ordering Information

PART NUMBER	TEMP. RANGE (^{o}C)	PACKAGE
CD54HC123F3A	-55 to 125	16 Ld CERDIP
CD54HCT123F3A	-55 to 125	16 Ld CERDIP
CD74HC123E	-55 to 125	16 Ld PDIP
CD74HC123M	-55 to 125	16 Ld SOIC
CD74HC123MT	-55 to 125	16 Ld SOIC
CD74HC123M96	-55 to 125	16 Ld SOIC
CD74HC123NSR	-55 to 125	16 Ld SOP
CD74HC123PW	-55 to 125	16 Ld TSSOP
CD74HC123PWR	-55 to 125	16 Ld TSSOP
CD74HC123PWT	-55 to 125	16 Ld TSSOP
CD74HC423E	-55 to 125	16 Ld PDIP
CD74HC423M	-55 to 125	16 Ld SOIC
CD74HC423MT	-55 to 125	16 Ld SOIC
CD74HC423M96	-55 to 125	16 Ld SOIC
CD74HC423NSR	-55 to 125	16 Ld SOP
CD74HCT123E	-55 to 125	16 Ld PDIP
CD74HCT123M	-55 to 125	16 Ld SOIC
CD74HCT123MT	-55 to 125	16 Ld SOIC
CD74HCT123M96	-55 to 125	16 Ld SOIC
CD74HCT423E	-55 to 125	16 Ld PDIP
CD74HCT423MT	-55 to 125	16 Ld SOIC
CD74HCT423M96	-55 to 125	16 Ld SOIC

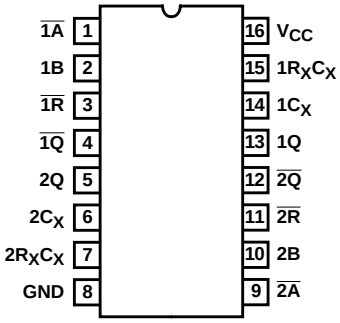
NOTE: When ordering, use the entire part number. The suffixes 96 and R denote tape and reel. The suffix T denotes a small-quantity reel of 250.

CAUTION: These devices are sensitive to electrostatic discharge. Users should follow proper IC Handling Procedures.

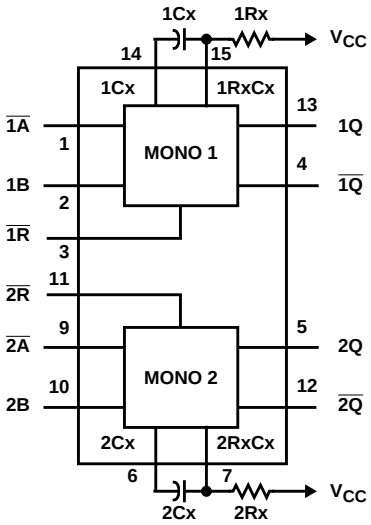
Copyright © 2003, Texas Instruments Incorporated

Pinout

CD54HC123, CD54HCT123
(CERDIP)
CD74HC123
(PDIP, SOIC, SOP, TSSOP)
CD74HC423
(PDIP, SOIC, SOP)
CD74HCT123, CD74HCT423
(PDIP, SOIC)
TOP VIEW



Functional Diagram



TRUTH TABLE

INPUTS			OUTPUTS	
$\overline{A}$	B	$\overline{R}$	Q	$\overline{Q}$
CD74HC/HCT123				
H	X	H	L	H
X	L	H	L	H
L	↑	H	⎍	⎍
↓	H	H	⎍	⎍
X	X	L	L	H
L	H	↑	⎍	⎍
CD74HC/HCT423				
H	X	H	L	H
X	L	H	L	H
L	↑	H	⎍	⎍
↓	H	H	⎍	⎍
X	X	L	L	H

H = High Voltage Level, L = Low Voltage Level,
X = Don't Care.

Absolute Maximum Ratings

DC Supply Voltage, V_{CC} . . . . . -0.5V to 7V
DC Input Diode Current, I_{IK}
For V_I < -0.5V or V_I > V_{CC} + 0.5V . . . . . ±20mA
DC Output Diode Current, I_{OK}
For V_O < -0.5V or V_O > V_{CC} + 0.5V . . . . . ±20mA
DC Output Source or Sink Current per Output Pin, I_O
For V_O > -0.5V or V_O < V_{CC} + 0.5V . . . . . ±25mA
DC V_{CC} or Ground Current, I_{CC} or I_{GND} . . . . . ±50mA

Operating Conditions

Temperature Range (T_A) . . . . . -55°C to 125°C
Supply Voltage Range, V_{CC}
HC Types . . . . . 2V to 6V
HCT Types . . . . . 4.5V to 5.5V
DC Input or Output Voltage, V_I, V_O . . . . . 0V to V_{CC}
Input Rise and Fall Time
2V . . . . . 1000ns (Max)
4.5V. . . . . 500ns (Max)
6V . . . . . 400ns (Max)

Thermal Information

Package Thermal Impedance, θ_{JA} (see Note 1):
E (PDIP) Package . . . . . 67°C/W
M (SOIC) Package. . . . . 73°C/W
NS (SOP) Package . . . . . 64°C/W
PW (TSSOP) Package . . . . . 108°C/W
Maximum Junction Temperature . . . . . 150°C
Maximum Storage Temperature Range . . . . . -65°C to 150°C
Maximum Lead Temperature (Soldering 10s) . . . . . 300°C
(SOIC - Lead Tips Only)

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTE:

1. The package thermal impedance is calculated in accordance with JESD 51-7.

DC Electrical Specifications

PARAMETER	SYMBOL	TEST CONDITIONS		V_{CC} (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
		V_I (V)	I_O (mA)		MIN	TYP	MAX	MIN	MAX	MIN	MAX	
HC TYPES												
High Level Input Voltage	V_{IH}	-	-	2	1.5	-	-	1.5	-	1.5	-	V
				4.5	3.15	-	-	3.15	-	3.15	-	V
				6	4.2	-	-	4.2	-	4.2	-	V
Low Level Input Voltage	V_{IL}	-	-	2	-	-	0.5	-	0.5	-	0.5	V
				4.5	-	-	1.35	-	1.35	-	1.35	V
				6	-	-	1.8	-	1.8	-	1.8	V
High Level Output Voltage CMOS Loads	V_{OH}	V_{IH} or V_{IL}	-0.02	2	1.9	-	-	1.9	-	1.9	-	V
			-0.02	4.5	4.4	-	-	4.4	-	4.4	-	V
			-0.02	6	5.9	-	-	5.9	-	5.9	-	V
High Level Output Voltage TTL Loads			-	-	-	-	-	-	-	-	-	V
			-4	4.5	3.98	-	-	3.84	-	3.7	-	V
			-5.2	6	5.48	-	-	5.34	-	5.2	-	V
Low Level Output Voltage CMOS Loads	V_{OL}	V_{IH} or V_{IL}	0.02	2	-	-	0.1	-	0.1	-	0.1	V
			0.02	4.5	-	-	0.1	-	0.1	-	0.1	V
			0.02	6	-	-	0.1	-	0.1	-	0.1	V
Low Level Output Voltage TTL Loads			-	-	-	-	-	-	-	-	-	V
			4	4.5	-	-	0.26	-	0.33	-	0.4	V
			5.2	6	-	-	0.26	-	0.33	-	0.4	V
Input Leakage Current	I_I	V_{CC} or GND	-	6	-	-	±0.1	-	±1	-	±1	µA
Quiescent Device Current	I_{CC}	V_{CC} or GND	0	6	-	-	8	-	80	-	160	µA

DC Electrical Specifications (Continued)

PARAMETER	SYMBOL	TEST CONDITIONS		V_{CC} (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
		V_I (V)	I_O (mA)		MIN	TYP	MAX	MIN	MAX	MIN	MAX	
HCT TYPES												
High Level Input Voltage	V_{IH}	-	-	4.5 to 5.5	2	-	-	2	-	2	-	V
Low Level Input Voltage	V_{IL}	-	-	4.5 to 5.5	-	-	0.8	-	0.8	-	0.8	V
High Level Output Voltage CMOS Loads	V_{OH}	V_{IH} or V_{IL}	-0.02	4.5	4.4	-	-	4.4	-	4.4	-	V
High Level Output Voltage TTL Loads			-4	4.5	3.98	-	-	3.84	-	3.7	-	V
Low Level Output Voltage CMOS Loads	V_{OL}	V_{IH} or V_{IL}	0.02	4.5	-	-	0.1	-	0.1	-	0.1	V
Low Level Output Voltage TTL Loads			4	4.5	-	-	0.26	-	0.33	-	0.4	V
Input Leakage Current	I_I	V_{CC} and GND	0	5.5	-		±0.1	-	±1	-	±1	µA
Quiescent Device Current	I_{CC}	V_{CC} or GND	0	5.5	-	-	8	-	80	-	160	µA
Additional Quiescent Device Current Per Input Pin: 1 Unit Load	ΔI_{CC} (Note 2)	V_{CC} -2.1	-	4.5 to 5.5	-	100	360	-	450	-	490	µA

NOTE:

2. For dual-supply systems theoretical worst case (V_I = 2.4V, V_{CC} = 5.5V) specification is 1.8mA.

HCT Input Loading Table

INPUT	UNIT LOADS
All	0.35

NOTE: Unit Load is ΔI_{CC} limit specified in DC Electrical Table, e.g. 360µA max at 25°C.

Prerequisite for Switching Specifications

PARAMETER	SYMBOL	V_{CC} (V)	25°C			-40°C TO 85°C			-55°C TO 125°C			UNITS
			MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	
HC TYPES												
Minimum Input, Pulse Width	t_{WL}											
$\overline{A}$		2	100	-	-	125	-	-	150	-	-	ns
		4.5	20	-	-	25	-	-	30	-	-	ns
		6	17	-	-	21	-	-	26	-	-	ns
B	t_{WH}	2	100	-	-	125	-	-	150	-	-	ns
		4.5	20	-	-	25	-	-	30	-	-	ns
		6	17	-	-	21	-	-	26	-	-	ns

Prerequisite for Switching Specifications (Continued)

PARAMETER	SYMBOL	V_{CC} (V)	25°C			-40°C TO 85°C			-55°C TO 125°C			UNITS
			MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	
$\overline{R}$	t_{WL}	2	100	-	-	125	-	-	150	-	150	ns
		4.5	20	-	-	25	-	-	30	-	30	ns
		6	17	-	-	21	-	-	26	-	26	ns
$\overline{A}$ and B Hold Time	t_H	2	50	-	-	65	-	-	75	-	75	ns
		4.5	10	-	-	13	-	-	15	-	15	ns
		6	9	-	-	11	-	-	13	-	13	ns
Reset Removal Time	t_{REM}	2	50	-	-	65	-	-	75	-	75	ns
		4.5	10	-	-	13	-	-	15	-	15	ns
		6	9	-	-	11	-	-	13	-	13	ns
Retrigger Time Number	t_{rT}	5	-	-	-	-	-	-	-	-	-	ns
R_X = 10KΩ, C_X = 0			-	50	-	-	63	-	-	76	-	ns
Output Pulse Width Q or $\overline{Q}$ R_X = 10KΩ, C_X = 10nF	t_W	5	40	-	50	38.7	-	51.3	38.2	-	51.8	µs
HCT TYPES												
Minimum Input, Pulse Width $\overline{A}$	t_{WL}	5	20	-	-	25	-	-	30	-	-	- ns
B	t_{WH}		20	-	-	25	-	-	30	-	-	ns
$\overline{R}$	t_{WL}		20	-	-	25	-	-	30	-	-	ns
$\overline{A}$ and B Hold Time	t_H	5	10	-	-	13	-	-	15	-	-	ns
Reset Removal Time	t_{REM}	5	10	-	-	13	-	-	15		-	ns
Retrigger Time Number (Note 3) R_X = 10KΩ, C_X = 0	t_{rT}	5	-	50	-	-	63	-	-	76	-	ns
Output Pulse Width Q or Q R_X = 10KΩ, C_X = 10nF	t_W	5	40	-	50	38.7	-	51.3	38.2	-	51.8	µs

NOTE:

3. Time to trigger depends on the values of R_X and C_X. The output pulse width can only be extended when the time between the active-going edges of the trigger input pulses meet the minimum retrigger time requirement.

Switching Specifications Input t_r, t_f = 6ns, R_X = 10KΩ, C_X = 0

PARAMETER	SYMBOL	TEST CONDITIONS	V_{CC} (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
HC TYPES											
Trigger Propagation Delay $\overline{A}$, B, $\overline{R}$ to Q	t_{PLH}	C_L = 50pF	2	-	-	300	-	375	-	450	ns
			4.5	-	-	60	-	75	-	90	ns
		C_L = 15pF	5	-	25	-	-	-	-	-	ns
		C_L = 50pF	6	-	-	51	-	64	-	76	ns
$\overline{A}$, B, $\overline{R}$ to $\overline{Q}$	t_{PHL}	C_L = 50pF	2	-	-	320	-	400	-	480	ns
			4.5	-	-	64	-	80	-	96	ns
		C_L = 15pF	5	-	26	-	-	-	-	-	ns
		C_L = 50pF	6	-	-	54	-	68	-	82	ns
Reset Propagation Delay $\overline{R}$ to Q or $\overline{Q}$	t_{PHL}, t_{PLH}	C_L = 50pF	2	-	-	215	-	270	-	325	ns
			4.5	-	-	43	-	54	-	65	ns
			6	-	-	37	-	46	-	55	ns
Output Transition Time	t_{THL}, t_{TLH}	C_L = 50pF	2	-	-	75	-	95	-	110	ns
			4.5	-	-	15	-	19	-	22	ns
			6	-	-	13	-	16	-	19	ns
Output Pulse Width R_X = 10KΩ, C_X = 10nF	-	-	5	-	45	-	-	-	-	-	µs
Pulse Width Match Between Circuits In the Same Package R_X = 10KΩ, C_X = 10pF	-	-	5	-	±2	-	-	-	-	-	%
Power Dissipation Capacitance (Note 4)	C_{PD}	C_L = 15pF	5	-	-	-	-	-	-	-	pF
Input Capacitance	C_{IN}	C_L = 50pF	-	10	-	10	-	10	-	10	pF
HCT TYPES											
Trigger Propagation Delay $\overline{A}$, B, $\overline{R}$ to $\overline{Q}$	t_{PLH}	C_L = 50pF	4.5	-	-	60	-	75	-	90	ns
		C_L = 15pF	5	-	25	-	-	-	-	-	ns
$\overline{A}$, B, $\overline{R}$ to $\overline{Q}$	t_{PHL}	C_L = 50pF	4.5	-	-	68	-	85	-	102	ns
		C_L =15pF	5	-	27	-	-	-	-	-	ns
Reset Propagation Delay $\overline{R}$ to Q or $\overline{Q}$	t_{PHL}, t_{PLH}	C_L = 50pF	4.5	-	-	48	-	60	-	72	ns
Output Transition Time	t_{THL}, t_{TLH}	C_L = 50pF	4.5	-	-	15	-	19	-	22	ns
Output Pulse Width R_X = 10KΩ, C_X = 10nF	-	-	5	-	45	-	-	-	-	-	µs

Switching Specifications Input t_r, t_f = 6ns, R_X = 10KΩ, C_X = 0 **(Continued)**

PARAMETER	SYMBOL	TEST CONDITIONS	V_{CC} (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
Pulse Width Match Between Circuits In the Same Package R_X = 10KΩ, C_X = 10pF	-	-	5		±2	-	-	-	-	-	%
Input Capacitance	C_{IN}	C_L = 50pF	-	-	-	10	-	10	-	10	pF

NOTE:

4. C_{PD} is used to determine the dynamic power consumption, per multivibrator.
   $P_D = (C_{PD} + C_X) V_{CC}^2 f_i \Sigma(C_L V_{CC}^2 f_O)$
   Where
   f_i = input frequency
   f_O = Output Frequency
   C_L = Output Load Capacitance
   C_X = External Capacitance
   V_{CC} = Supply Voltage,
   assuming $f_i \ll \frac{1}{t_W}$

Test Circuits and Waveforms

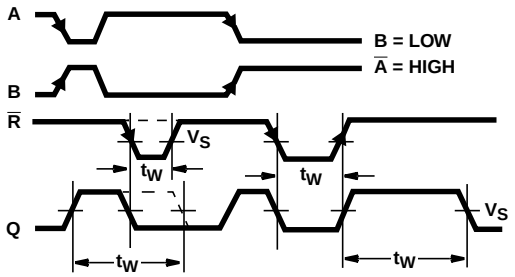


FIGURE 1. OUTPUT PULSE CONTROL USING RESET INPUT ($\overline{R}$) PULSE FOR 123

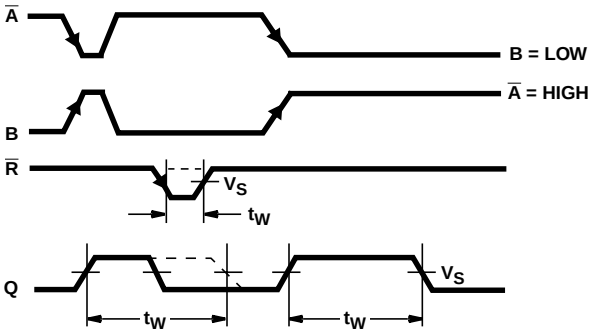
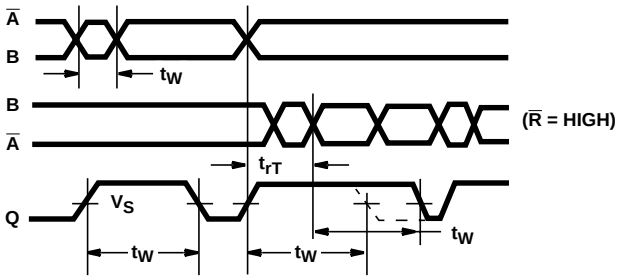


FIGURE 2. OUTPUT PULSE CONTROL USING RESET INPUT ($\overline{R}$) FOR 423



NOTE: Output pulse control using retrigger pulse for 123 and 423.

FIGURE 3. TRIGGERING OF ONE SHOT BY INPUT $\overline{A}$ OR INPUT B FOR A PERIOD t_W

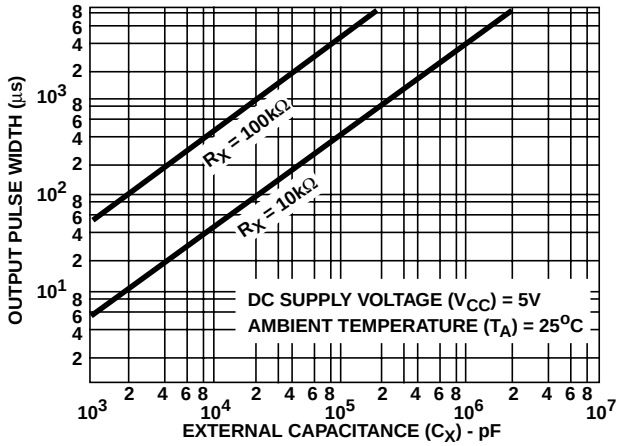


FIGURE 4. TYPICAL OUTPUT PULSE WIDTH AS A FUNCTION OF C_X FOR R_X = 10kΩ AND 100kΩ

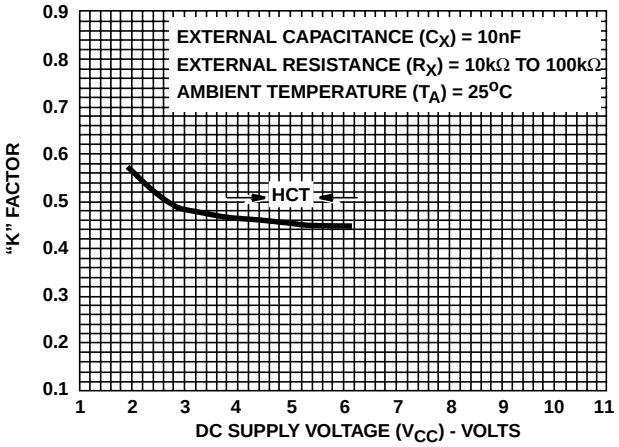


FIGURE 5. TYPICAL "K" FACTOR AS A FUNCTION OF V_{CC}

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
5962-8684701EA	Active	Production	CDIP (J) | 16	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8684701EA CD54HC123F3A
5962-8970001EA	Active	Production	CDIP (J) | 16	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8970001EA CD54HCT123F3A
CD54HC123F	Active	Production	CDIP (J) | 16	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	CD54HC123F
CD54HC123F.A	Active	Production	CDIP (J) | 16	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	CD54HC123F
CD54HC123F3A	Active	Production	CDIP (J) | 16	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8684701EA CD54HC123F3A
CD54HC123F3A.A	Active	Production	CDIP (J) | 16	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8684701EA CD54HC123F3A
CD54HCT123F3A	Active	Production	CDIP (J) | 16	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8970001EA CD54HCT123F3A
CD54HCT123F3A.A	Active	Production	CDIP (J) | 16	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8970001EA CD54HCT123F3A
CD74HC123E	Active	Production	PDIP (N) | 16	25 | TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD74HC123E
CD74HC123E.A	Active	Production	PDIP (N) | 16	25 | TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD74HC123E
CD74HC123EE4	Active	Production	PDIP (N) | 16	25 | TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD74HC123E
CD74HC123M	Obsolete	Production	SOIC (D) | 16	-	-	Call TI	Call TI	-55 to 125	HC123M
CD74HC123M96	Active	Production	SOIC (D) | 16	2500 | LARGE T&R	Yes	NIPDAU | SN	Level-1-260C-UNLIM	-55 to 125	HC123M
CD74HC123M96.A	Active	Production	SOIC (D) | 16	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC123M
CD74HC123M96E4	Active	Production	SOIC (D) | 16	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC123M
CD74HC123M96G4	Active	Production	SOIC (D) | 16	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC123M
CD74HC123M96G4.A	Active	Production	SOIC (D) | 16	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC123M
CD74HC123NSR	Active	Production	SOP (NS) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC123M
CD74HC123NSR.A	Active	Production	SOP (NS) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC123M
CD74HC123PW	Obsolete	Production	TSSOP (PW) | 16	-	-	Call TI	Call TI	-55 to 125	HJ123
CD74HC123PWR	Active	Production	TSSOP (PW) | 16	2000 | LARGE T&R	Yes	NIPDAU | SN	Level-1-260C-UNLIM	-55 to 125	HJ123
CD74HC123PWR.A	Active	Production	TSSOP (PW) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HJ123
CD74HC123PWRG4	Active	Production	TSSOP (PW) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HJ123
CD74HC123PWRG4.A	Active	Production	TSSOP (PW) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HJ123
CD74HC123PWT	Obsolete	Production	TSSOP (PW) | 16	-	-	Call TI	Call TI	-55 to 125	HJ123

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
CD74HC423E	Active	Production	PDIP (N) | 16	25 | TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD74HC423E
CD74HC423E.A	Active	Production	PDIP (N) | 16	25 | TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD74HC423E
CD74HC423M	Obsolete	Production	SOIC (D) | 16	-	-	Call TI	Call TI	-55 to 125	HC423M
CD74HC423M96	Active	Production	SOIC (D) | 16	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC423M
CD74HC423M96.A	Active	Production	SOIC (D) | 16	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC423M
CD74HC423M96G4	Active	Production	SOIC (D) | 16	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC423M
CD74HC423NSR	Active	Production	SOP (NS) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC423M
CD74HC423NSR.A	Active	Production	SOP (NS) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC423M
CD74HCT123E	Active	Production	PDIP (N) | 16	25 | TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD74HCT123E
CD74HCT123E.A	Active	Production	PDIP (N) | 16	25 | TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD74HCT123E
CD74HCT123M	Obsolete	Production	SOIC (D) | 16	-	-	Call TI	Call TI	-55 to 125	HCT123M
CD74HCT123M96	Active	Production	SOIC (D) | 16	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT123M
CD74HCT123M96.A	Active	Production	SOIC (D) | 16	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT123M
CD74HCT123MT	Obsolete	Production	SOIC (D) | 16	-	-	Call TI	Call TI	-55 to 125	HCT123M
CD74HCT423E	Active	Production	PDIP (N) | 16	25 | TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD74HCT423E
CD74HCT423E.A	Active	Production	PDIP (N) | 16	25 | TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD74HCT423E
CD74HCT423M96	Active	Production	SOIC (D) | 16	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT423M
CD74HCT423M96.A	Active	Production	SOIC (D) | 16	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT423M
CD74HCT423M96G4	Active	Production	SOIC (D) | 16	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT423M
CD74HCT423MT	Obsolete	Production	SOIC (D) | 16	-	-	Call TI	Call TI	-55 to 125	HCT423M

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF CD54HC123, CD54HCT123, CD74HC123, CD74HCT123 :

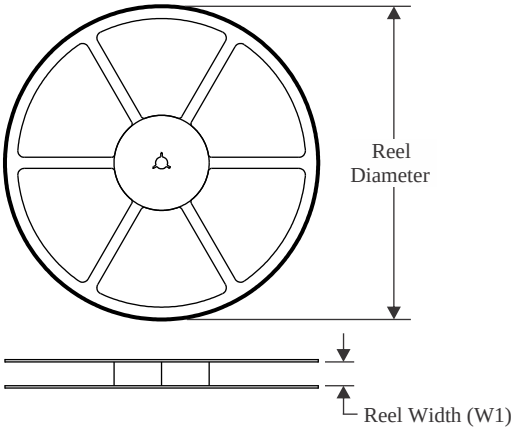
- Catalog : CD74HC123, CD74HCT123
- Military : CD54HC123, CD54HCT123

NOTE: Qualified Version Definitions:

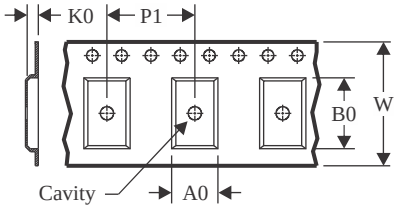
- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION

REEL DIMENSIONS

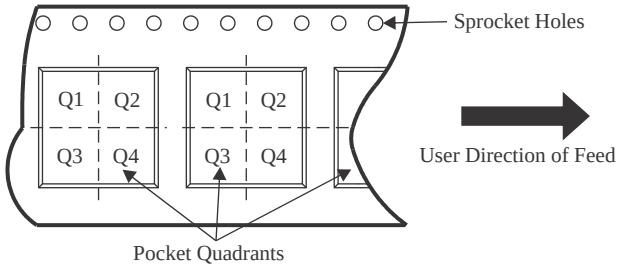


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

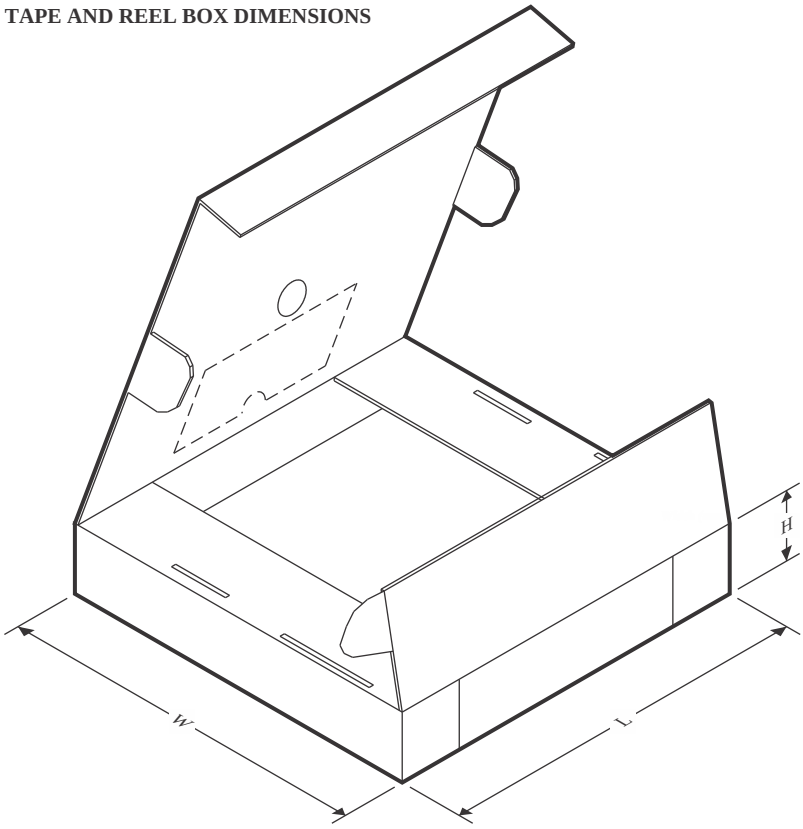
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD74HC123M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
CD74HC123M96G4	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
CD74HC123NSR	SOP	NS	16	2000	330.0	16.4	8.1	10.4	2.5	12.0	16.0	Q1
CD74HC123PWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
CD74HC123PWRG4	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
CD74HC423M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
CD74HC423NSR	SOP	NS	16	2000	330.0	16.4	8.1	10.4	2.5	12.0	16.0	Q1
CD74HCT123M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
CD74HCT423M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1

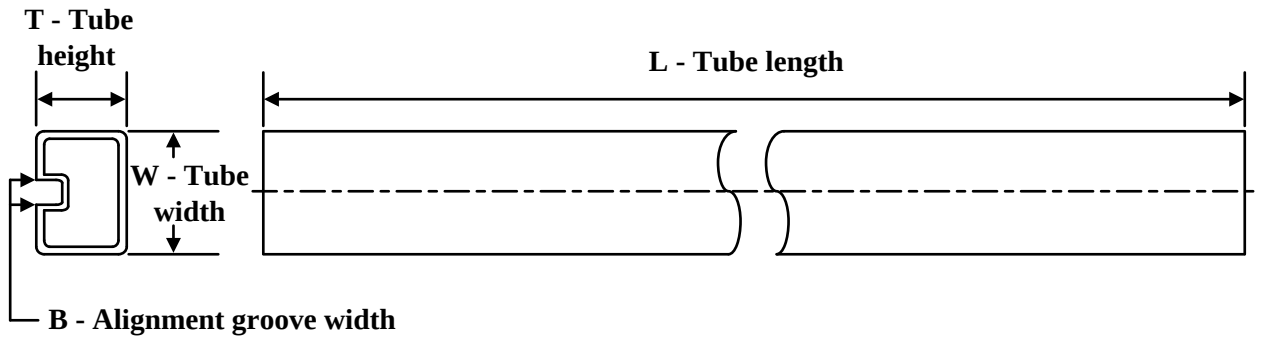
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

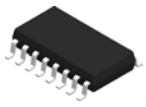
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD74HC123M96	SOIC	D	16	2500	353.0	353.0	32.0
CD74HC123M96G4	SOIC	D	16	2500	340.5	336.1	32.0
CD74HC123NSR	SOP	NS	16	2000	353.0	353.0	32.0
CD74HC123PWR	TSSOP	PW	16	2000	353.0	353.0	32.0
CD74HC123PWRG4	TSSOP	PW	16	2000	353.0	353.0	32.0
CD74HC423M96	SOIC	D	16	2500	353.0	353.0	32.0
CD74HC423NSR	SOP	NS	16	2000	353.0	353.0	32.0
CD74HCT123M96	SOIC	D	16	2500	353.0	353.0	32.0
CD74HCT423M96	SOIC	D	16	2500	353.0	353.0	32.0

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
CD74HC123E	N	PDIP	16	25	506	13.97	11230	4.32
CD74HC123E	N	PDIP	16	25	506	13.97	11230	4.32
CD74HC123E.A	N	PDIP	16	25	506	13.97	11230	4.32
CD74HC123E.A	N	PDIP	16	25	506	13.97	11230	4.32
CD74HC123EE4	N	PDIP	16	25	506	13.97	11230	4.32
CD74HC123EE4	N	PDIP	16	25	506	13.97	11230	4.32
CD74HC423E	N	PDIP	16	25	506	13.97	11230	4.32
CD74HC423E	N	PDIP	16	25	506	13.97	11230	4.32
CD74HC423E.A	N	PDIP	16	25	506	13.97	11230	4.32
CD74HC423E.A	N	PDIP	16	25	506	13.97	11230	4.32
CD74HCT123E	N	PDIP	16	25	506	13.97	11230	4.32
CD74HCT123E	N	PDIP	16	25	506	13.97	11230	4.32
CD74HCT123E.A	N	PDIP	16	25	506	13.97	11230	4.32
CD74HCT123E.A	N	PDIP	16	25	506	13.97	11230	4.32
CD74HCT423E	N	PDIP	16	25	506	13.97	11230	4.32
CD74HCT423E	N	PDIP	16	25	506	13.97	11230	4.32
CD74HCT423E.A	N	PDIP	16	25	506	13.97	11230	4.32
CD74HCT423E.A	N	PDIP	16	25	506	13.97	11230	4.32

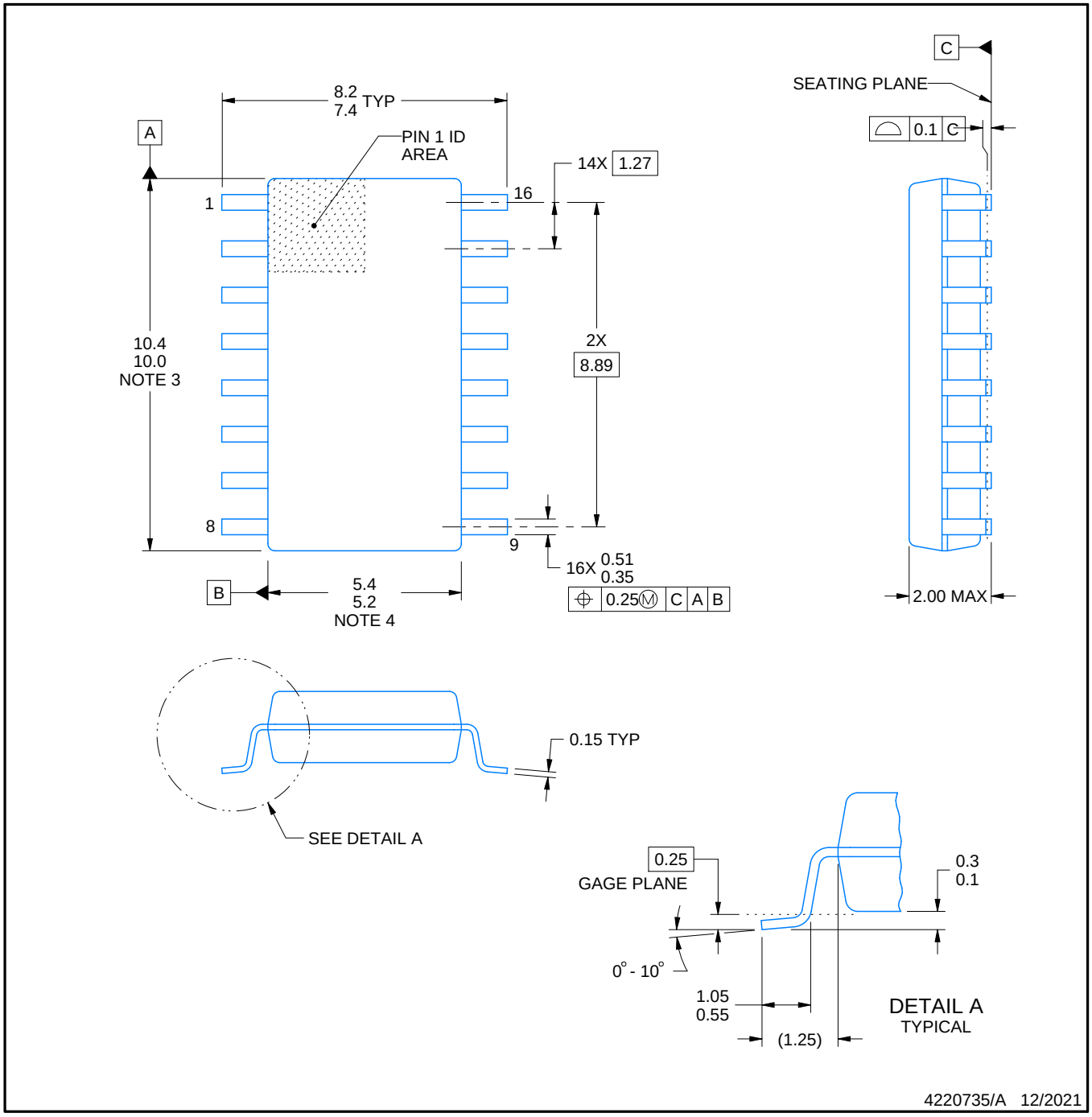


PACKAGE OUTLINE

NS0016A

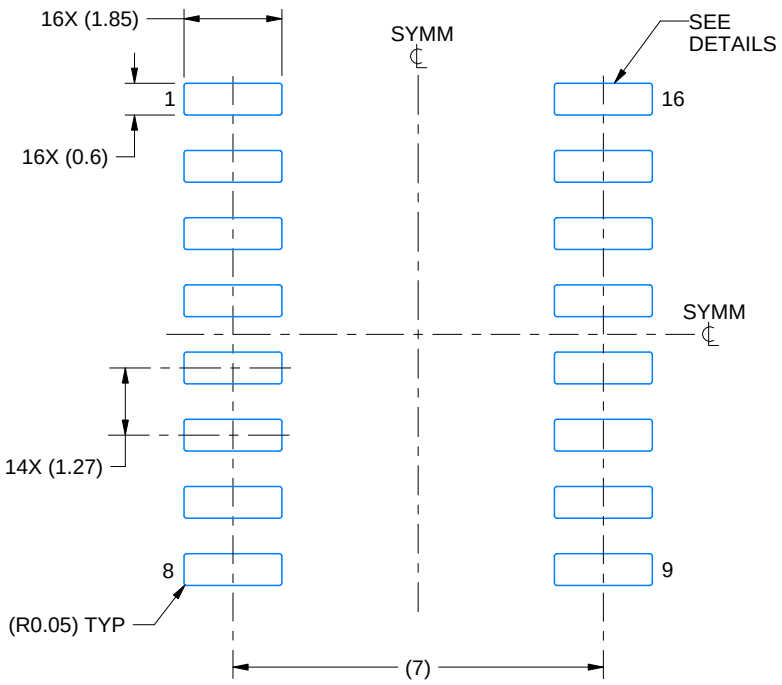
SOP - 2.00 mm max height

SOP

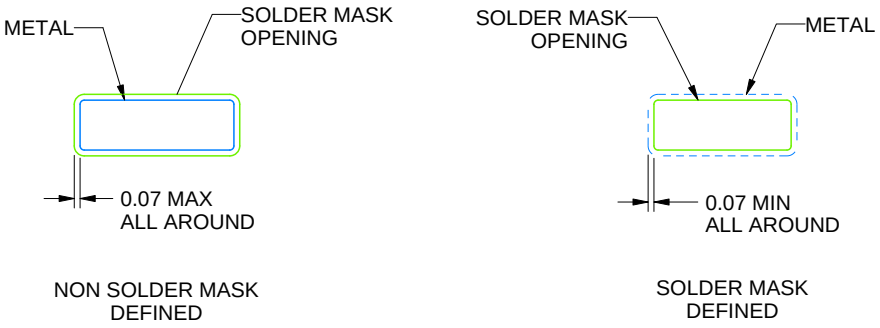


NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.



LAND PATTERN EXAMPLE
SCALE:7X



NON SOLDER MASK
DEFINED

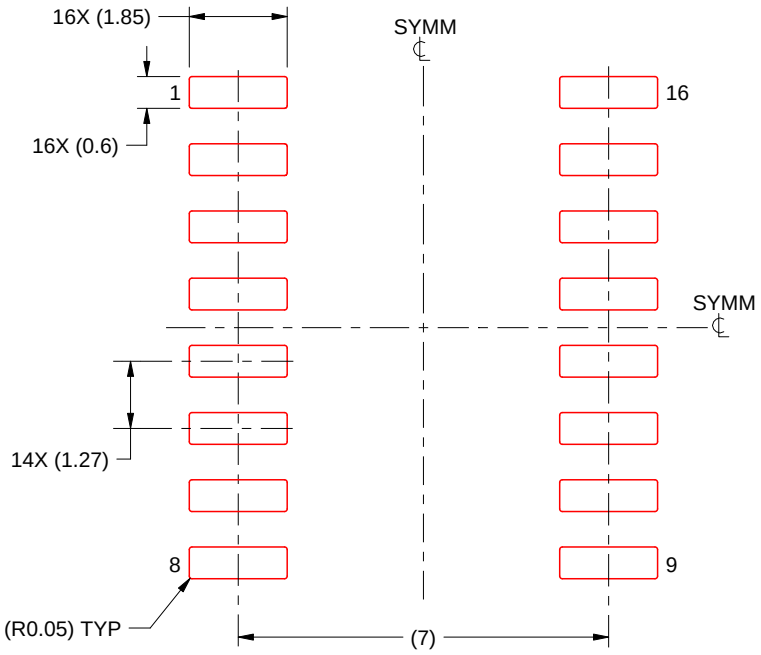
SOLDER MASK
DEFINED

SOLDER MASK DETAILS

4220735/A 12/2021

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



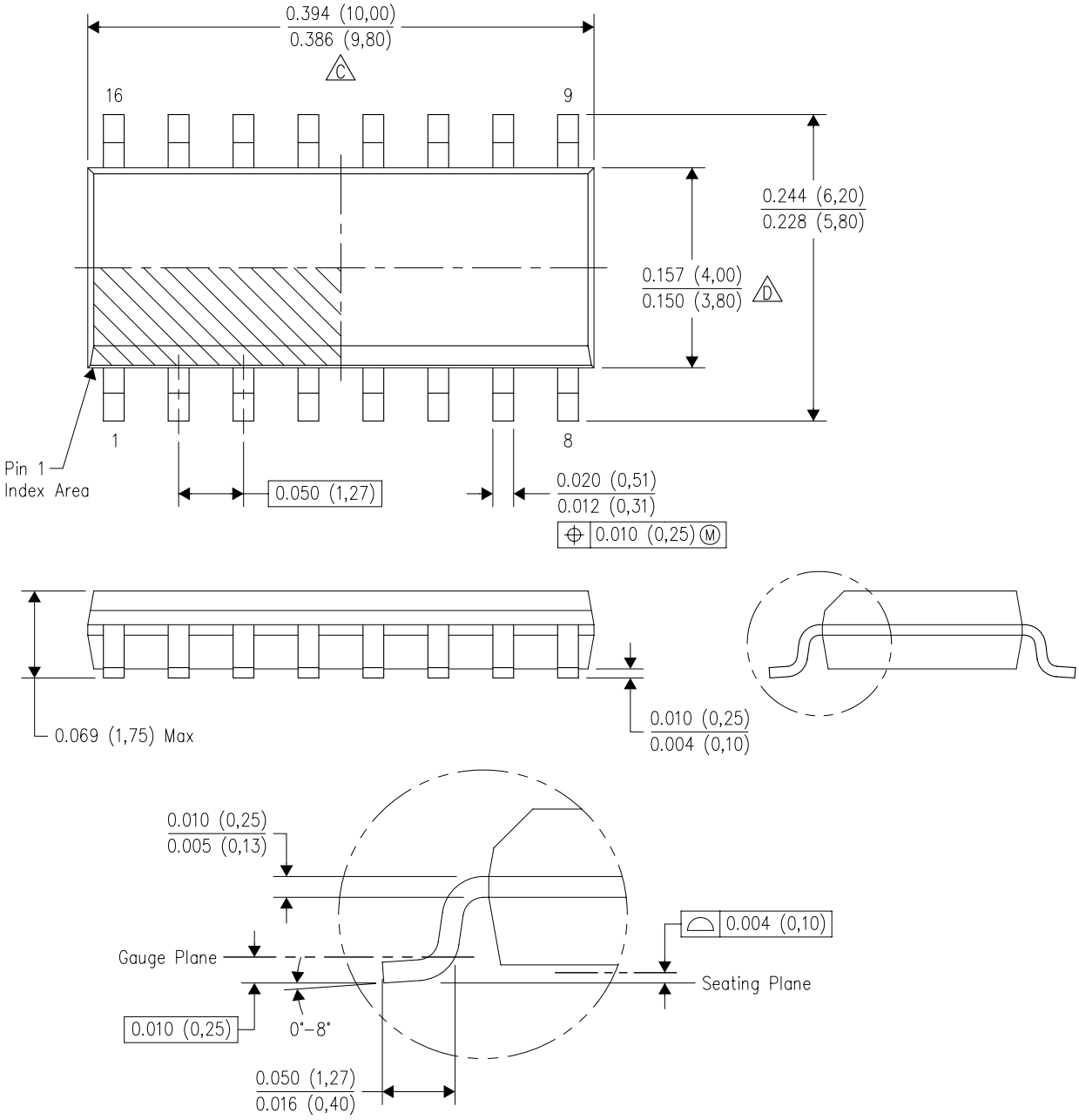
SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:7X

4220735/A 12/2021

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

D (R–PDSO–G16) PLASTIC SMALL OUTLINE

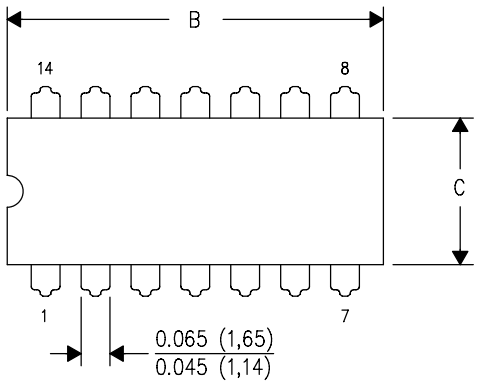


NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
E. Reference JEDEC MS–012 variation AC.

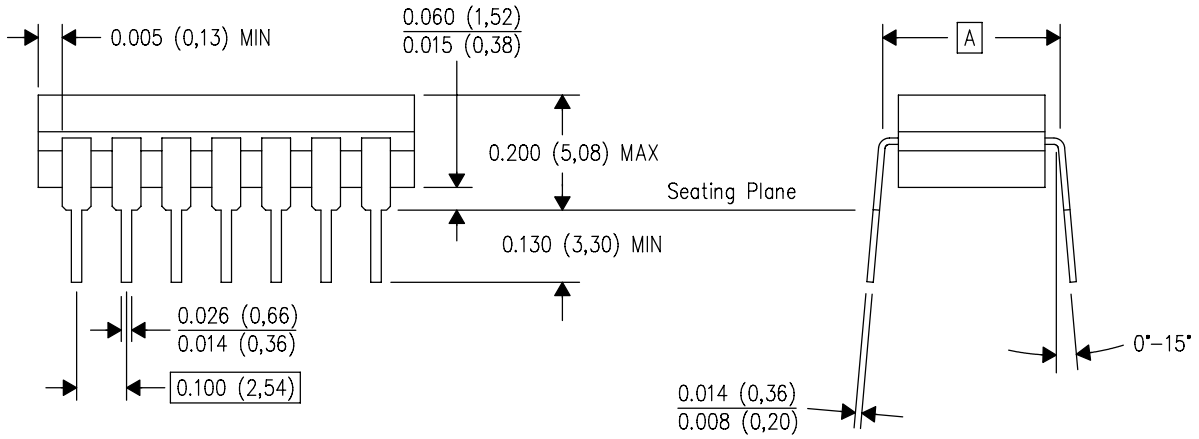
J (R–GDIP–T**)

14 LEADS SHOWN

CERAMIC DUAL IN–LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

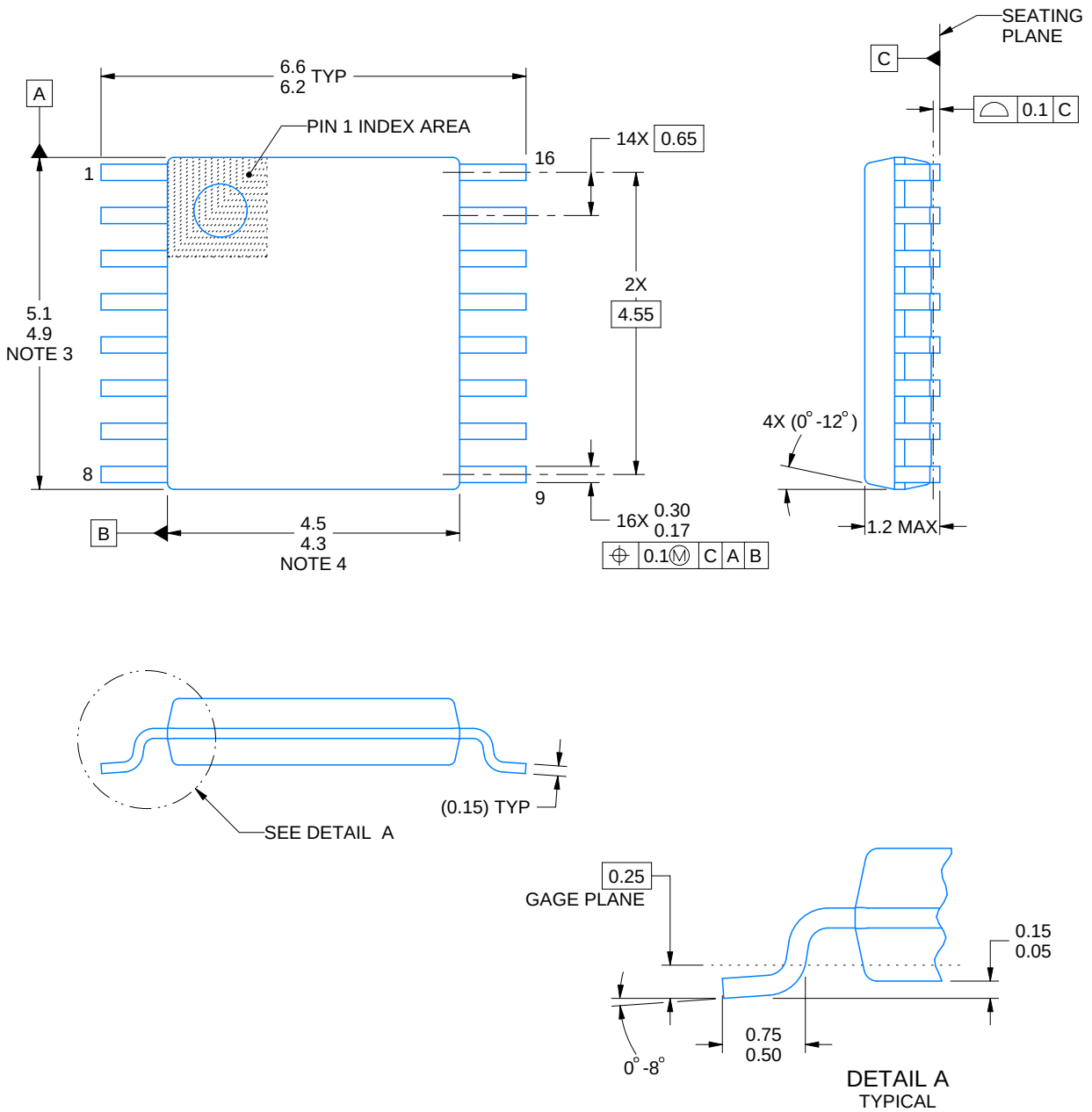
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1–T14, GDIP1–T16, GDIP1–T18 and GDIP1–T20.

PACKAGE OUTLINE

PW0016A

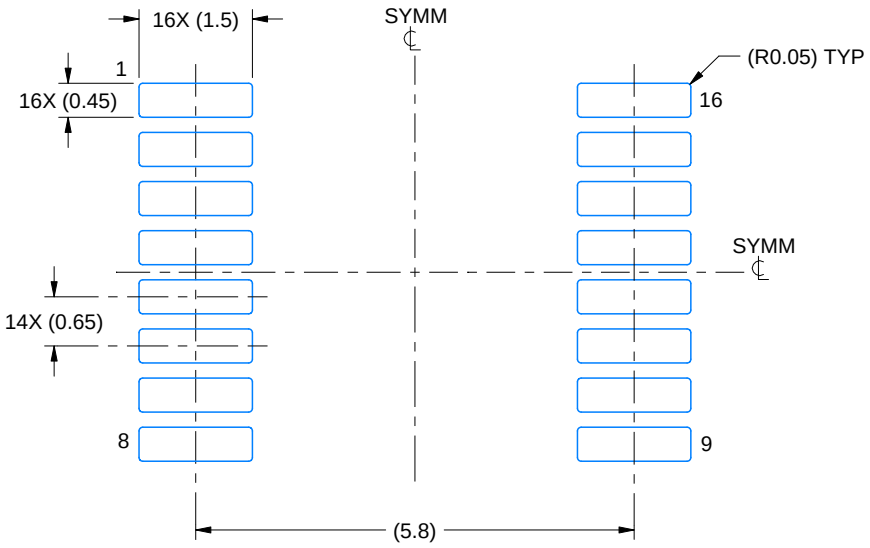
TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X

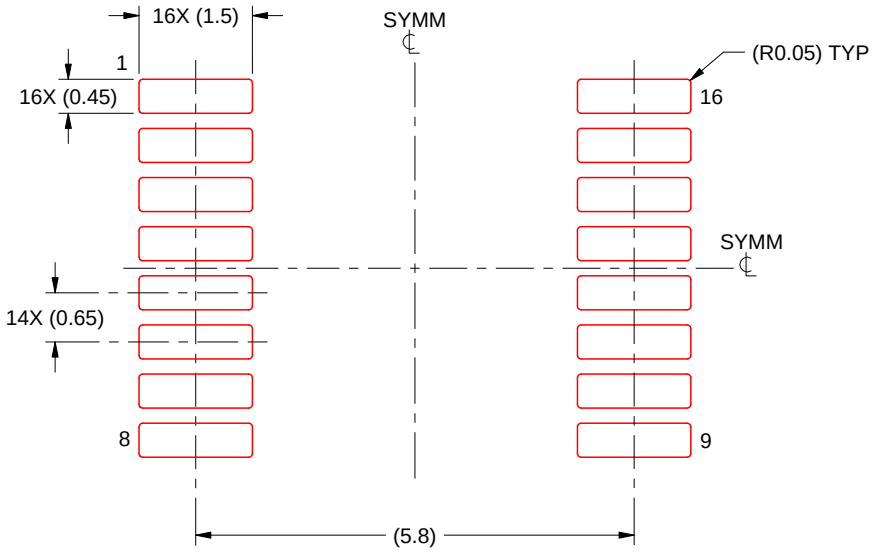


SOLDER MASK DETAILS

4220204/B 12/2023

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220204/B 12/2023

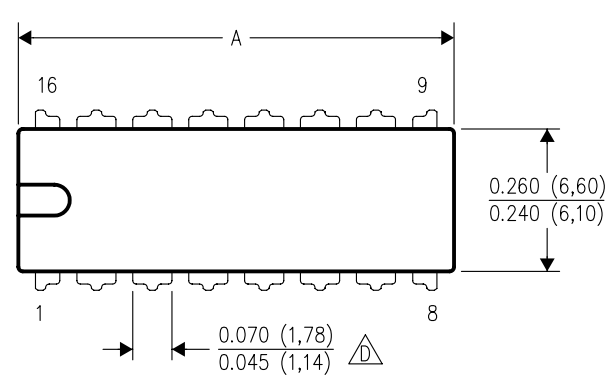
NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

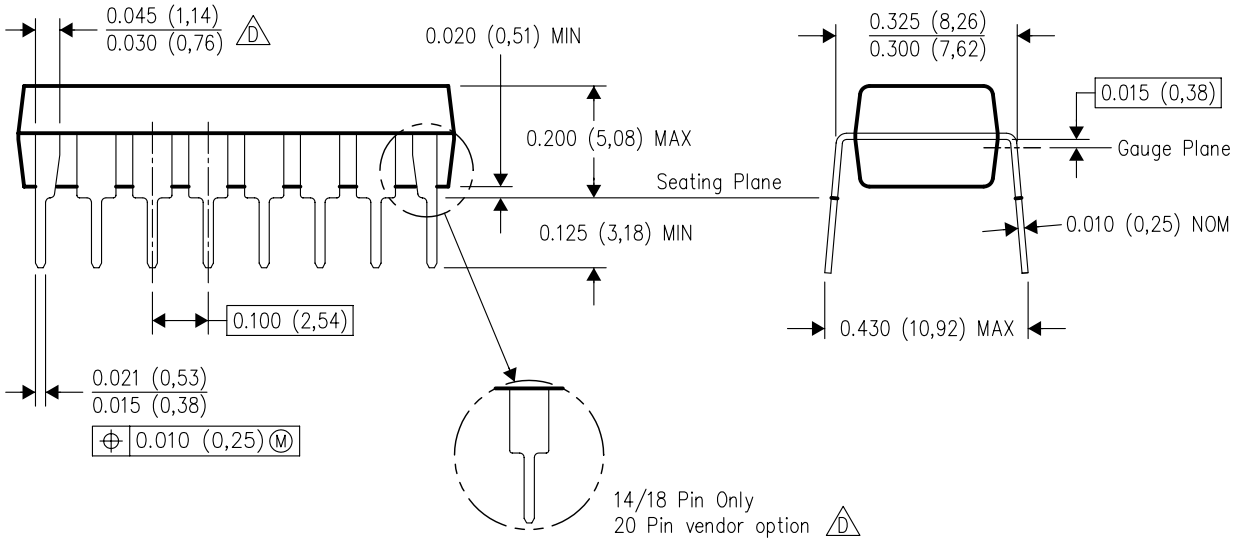
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES “AS IS” AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you fully indemnify TI and its representatives against any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI’s products are provided subject to TI’s Terms of Sale, TI’s General Quality Guidelines, or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI’s provision of these resources does not expand or otherwise alter TI’s applicable warranties or warranty disclaimers for TI products. Unless TI explicitly designates a product as custom or customer-specified, TI products are standard, catalog, general purpose devices.

TI objects to and rejects any additional or different terms you may propose.

Copyright © 2026, Texas Instruments Incorporated

Last updated 10/2025